

AMENDMENTS TO THE CLAIMS

The following Listing of Claims will replace all prior versions and listings of claims in the application:

Listing of Claims

Claims 1-23 (canceled)

24. (Amended) A silicon-backed microdisplay structure formed on a silicon substrate, the structure comprising:

- [a silicon substrate;]
- a silicon-side conductive layer [disposed] formed directly on the silicon substrate;
- a silicon-side passivation layer 2000-6000 angstroms thick [disposed] formed directly on the silicon-side conductive layer;
- a cover glass sheet;
- a glass-side conductive layer [disposed] formed directly on the cover glass sheet;
- a glass-side passivation layer [of a predetermined material and thickness disposed] formed directly on the glass-side conductive layer; and
- liquid crystal material [sandwiched] disposed directly between the glass-side passivation layer and the silicon-side passivation layer;

[wherein] the glass-side passivation layer [is] being about 300-900 angstroms thick and [comprises] comprising a material selected from the group consisting of  $\text{CeO}_2$ ,  $\text{In}_2\text{O}_3$ ,  $\text{MgO}$ ,  $\text{SnO}_2$ ,  $\text{Ta}_2\text{O}_5$ ,  $\text{TiO}_2$ ,  $\text{Y}_2\text{O}_3$ ,  $\text{SiO}_2$ ,  $\text{ZnO}$ ,  $\text{Al}_2\text{O}_3$ ,  $\text{BeO}$ ,  $\text{MgF}_2$  and combinations thereof,

such that the work function balance of said silicon-backed microdisplay is in the range of approximately 0.2eV to 0.4eV.

25. (Currently Pending) A silicon-backed microdisplay as in claim 24, and wherein the silicon-side conductive layer comprises aluminum.

26. (Currently Pending) A silicon-backed microdisplay as in claim 24, and wherein the silicon-side passivation layer comprises a silicon dioxide layer in combination with a silicon nitride layer.

27. (Amended) A silicon-backed microdisplay as in claim 24, and wherein the glass-side conductive layer comprises [a material that includes] Indium-tin oxide (ITO), has a characteristic resistance in the range of 100-500 ohms/square and a light transmissivity of 90% or greater.

28. (Currently pending) A silicon-backed microdisplay as in claim 24, and wherein the combination of the glass-side passivation layer and the glass-side conductive layer has an overall transmissivity of 90% or greater and a reflectivity of less than 1%.